华润微电子(重庆)有限公司

CRST060N08N3,CRSS057N08N3

SkyMOS3 N-MOSFET 80V, 5mΩ, 100A

Features

- Uses CRM(CQ) advanced SkyMOS3 technology
- Extremely low on-resistance $R_{DS(on)}$
- Excellent $Q_g x R_{DS(on)}$ product(FOM)
- Qualified according to JEDEC criteria

Applications

- Motor control and drive
- Battery management
- UPS (Uninterrupible Power Supplies)

Product Summary

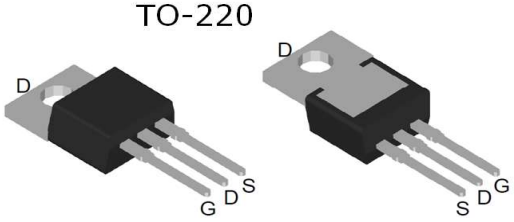
V_{DS}	80V
$R_{DS(on)}$	5mΩ
I_D	100A

100% DVDS Tested

100% Avalanche Tested

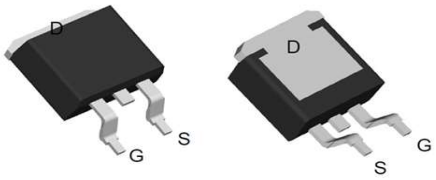
RoHS HF

TO-220

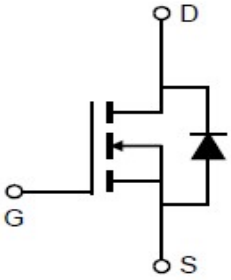


CRST060N08N3

TO-263



CRSS057N08N3



Package Marking and Ordering Information

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
CRST060N08N3	-	TO-220	Tube	N/A	N/A	50pcs
CRSS057N08N3	-	TO-263	Tape	N/A	N/A	1000pcs

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	80	V
Continuous drain current T_C = 25°C (Silicon limit) T_C = 25°C (Package limit) T_C = 100°C (Silicon limit)	I_D	 100 120 64	A
Pulsed drain current (T_C = 25°C, t_p limited by T_{jmax})	$I_{D\ pulse}$	400	A
Avalanche energy, single pulse (L=0.5mH, Rg=25Ω)	E_{AS}	132	mJ
Gate-Source voltage	V_{GS}	±20	V
Power dissipation (T_C = 25°C)	P_{tot}	109	W
Operating junction and storage temperature	T_j , T_{stg}	-55...+150	°C

※. Notes:1.EAS is tested at starting Tj = 25℃, L = 0.5mH, IAS = 23.0A, VGS = 10V.

©China Resources Microelectronics (Chongqing) Limited

Thermal Resistance

Parameter	Symbol	Max	Unit
Thermal resistance, junction – case.	R_{thJC}	1.15	°C/W
Thermal resistance, junction – ambient(min. footprint)	R_{thJA}	62.5	

Electrical Characteristic (at Tj = 25 °C, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Static Characteristic						
Drain-source breakdown voltage	BV_{DSS}	80	-	-	V	V_{GS}=0V, I_D=250uA
Gate threshold voltage	$V_{GS(th)}$	2.0	3.0	4.0	V	V_{DS}=V_{GS},I_D=250uA
Zero gate voltage drain current	I_{DSS}	- -	- -	1 100	μA	V_{DS}=80V,V_{GS}=0V T_j=25°C T_j=125°C
Gate-source leakage current	I_{GSS}	-	±10	±100	nA	V_{GS}=±20V,V_{DS}=0V
Drain-source on-state resistance	$R_{DS(on)}$	- -	5.0 4.7	6.0 5.7	mΩ	V_{GS}=10V, I_D=40A TO-220 TO-263
Transconductance	g_{fs}	-	74.5	-	S	V_{DS}=5V,I_D=40A
Dynamic Characteristic						
Input Capacitance	C_{iss}	-	3004.5	-	pF	V_{GS}=0V, V_{DS}=40V, f=1MHz
Output Capacitance	C_{oss}	-	715	-		
Reverse Transfer Capacitance	C_{rss}	-	48.5	-		
Gate Total Charge	Q_G	-	46.6	-	nC	V_{GS}=10V, V_{DS}=40V, I_D=40A, f=1MHz
Gate-Source charge	Q_{gs}	-	19.4	-		
Gate-Drain charge	Q_{gd}	-	10.2	-		
Turn-on delay time	$t_{d(on)}$	-	15.2	-	ns	V_{GS}=10V, V_{DD}=40V, R_{G_ext}=2.7Ω
Rise time	t_r	-	57	-		
Turn-off delay time	$t_{d(off)}$	-	29.7	-		
Fall time	t_f	-	41.7	-		
Gate resistance	R_G	-	1.65	-	Ω	V_{GS}=0V, V_{DS}=0V, f=1MHz

©China Resources Microelectronics (Chongqing) Limited

Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V_{SD}	-	0.91	1.3	V	V_{GS}=0V,I_{SD}=40A
Body Diode Reverse Recovery Time	t_{rr}	-	46.3	-	ns	I_F=40A, dI/dt=100A/μs
Body Diode Reverse Recovery Charge	Q_{rr}	-	59.1	-	nC	

©China Resources Microelectronics (Chongqing) Limited

Typical Performance Characteristics

Fig 1: Output Characteristics

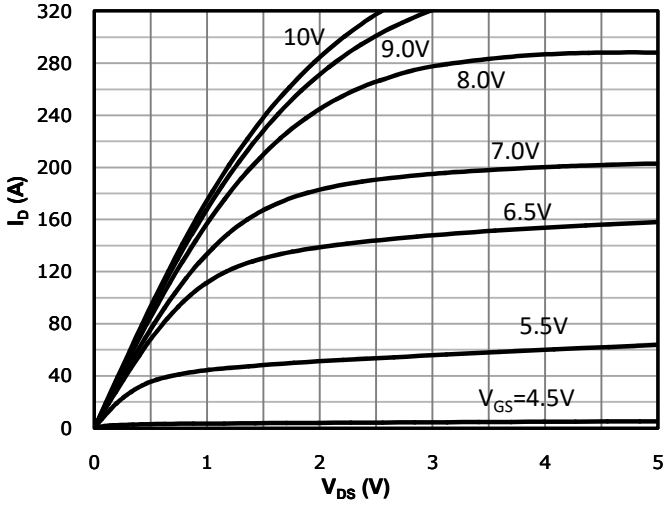


Fig 2: Transfer Characteristics

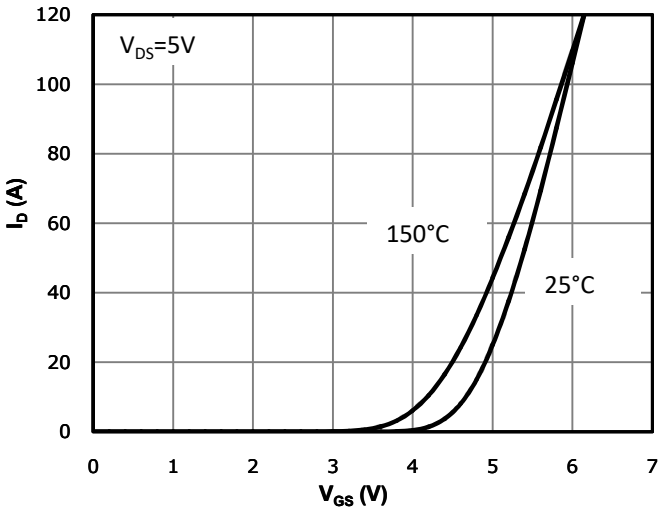


Fig 3: Rds(on) vs Drain Current and Gate Voltage

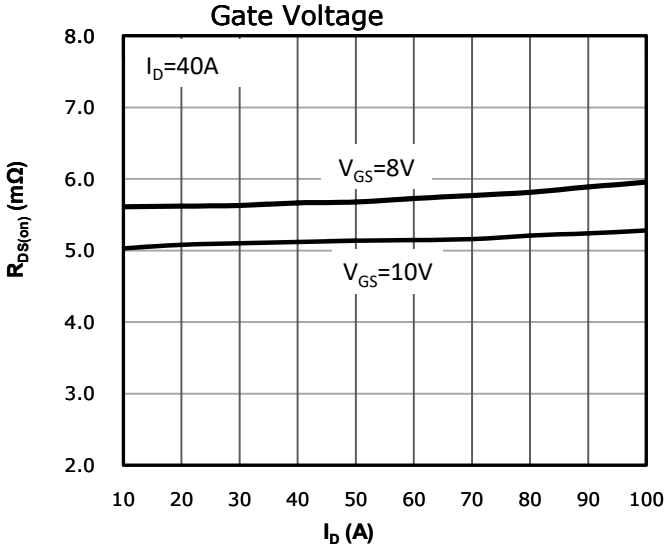


Fig 4: Rds(on) vs Gate Voltage

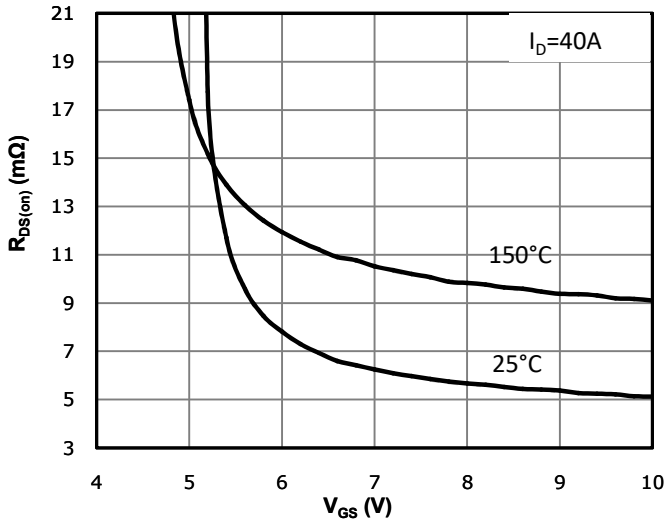


Fig 5: Rds(on) vs. Temperature

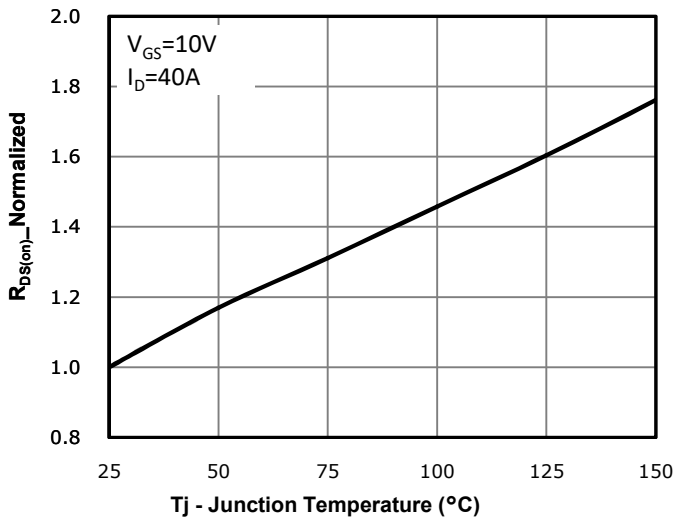
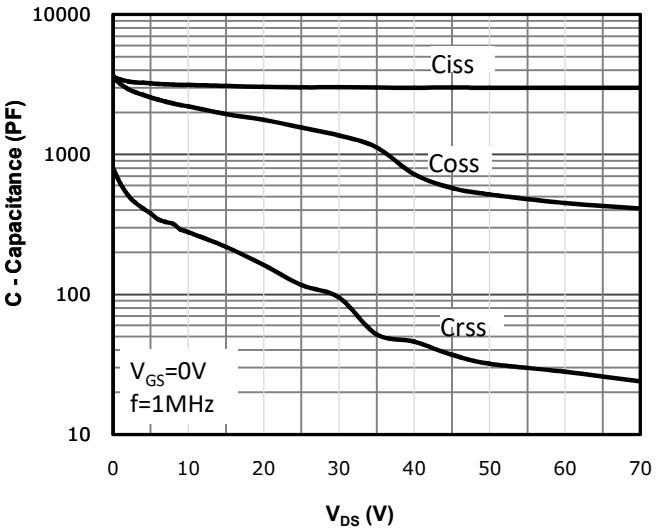


Fig 6: Capacitance Characteristics



©China Resources Microelectronics (Chongqing) Limited

Fig 7: Gate Charge Characteristics

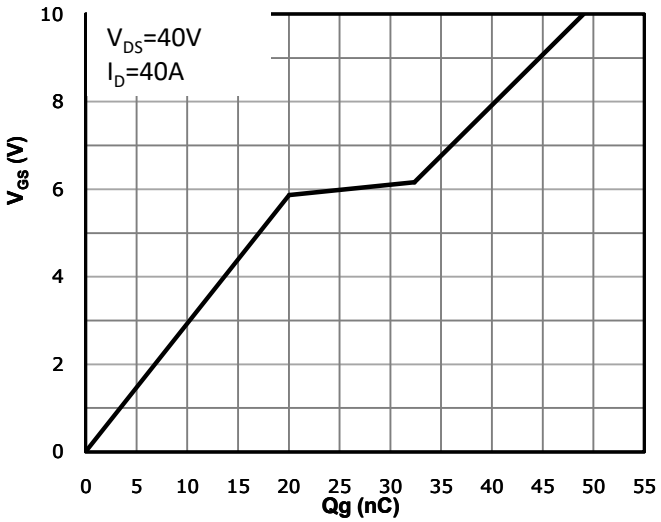


Fig 8: Body-diode Forward Characteristics

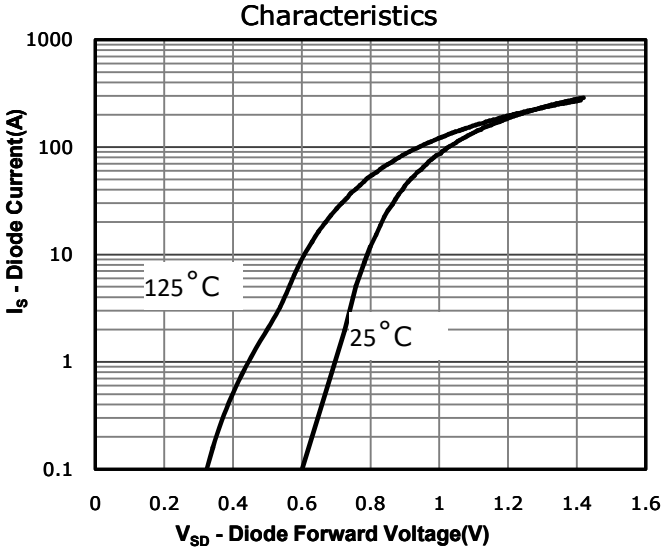


Fig 9: Power Dissipation

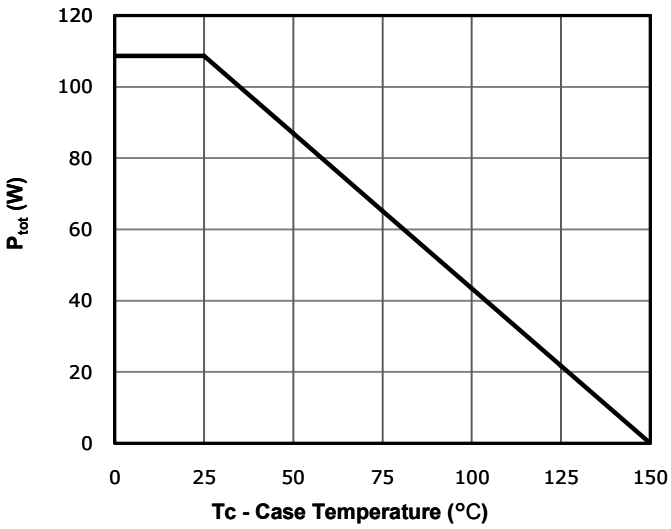


Fig 10: Drain Current Derating

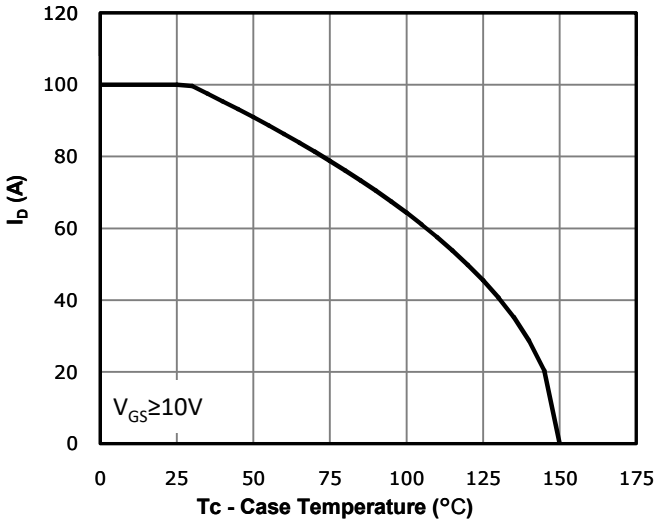
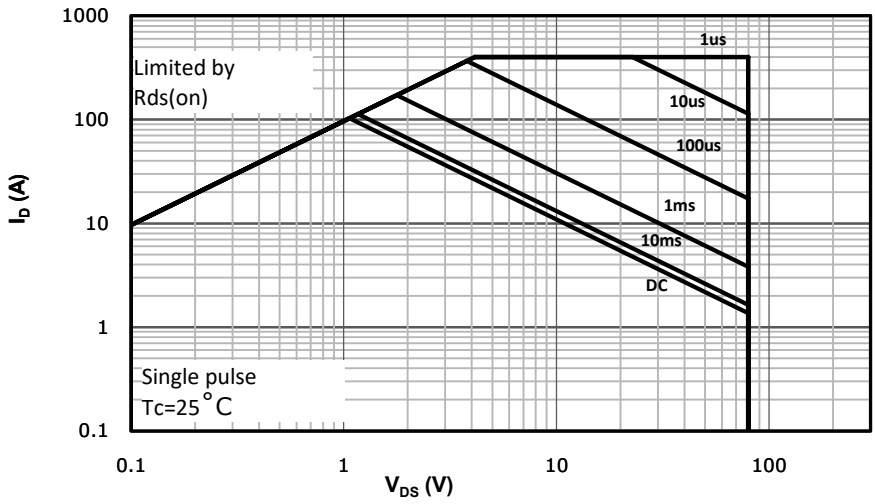
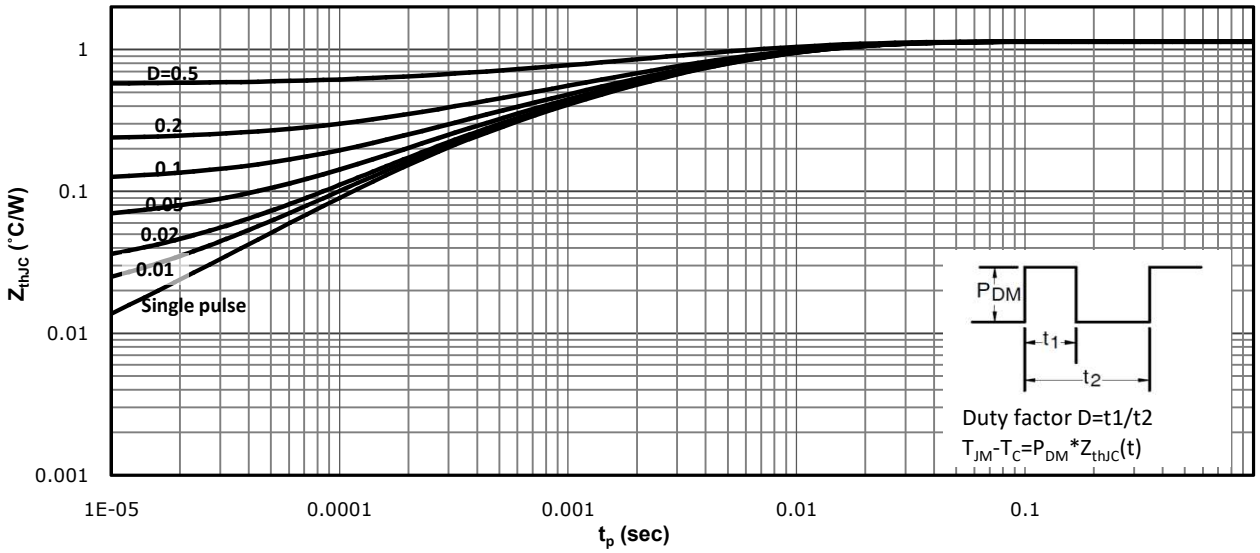


Fig 11: Safe Operating Area



©China Resources Microelectronics (Chongqing) Limited

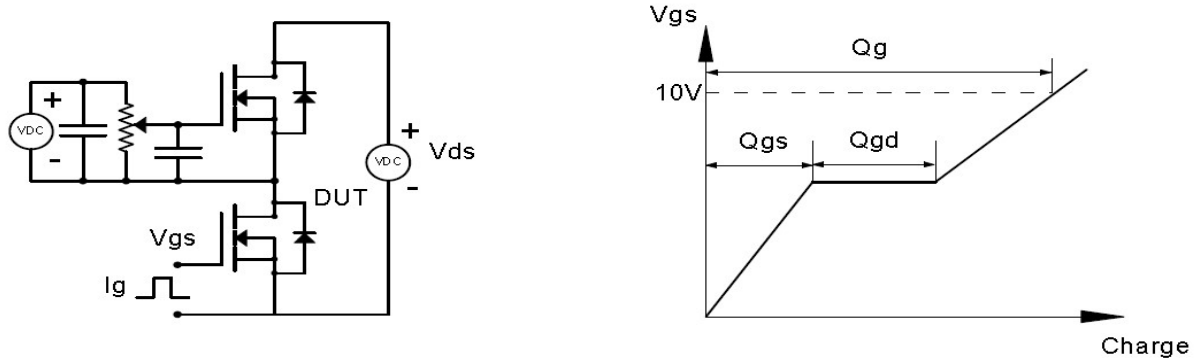
Fig 12: Max. Transient Thermal Impedance



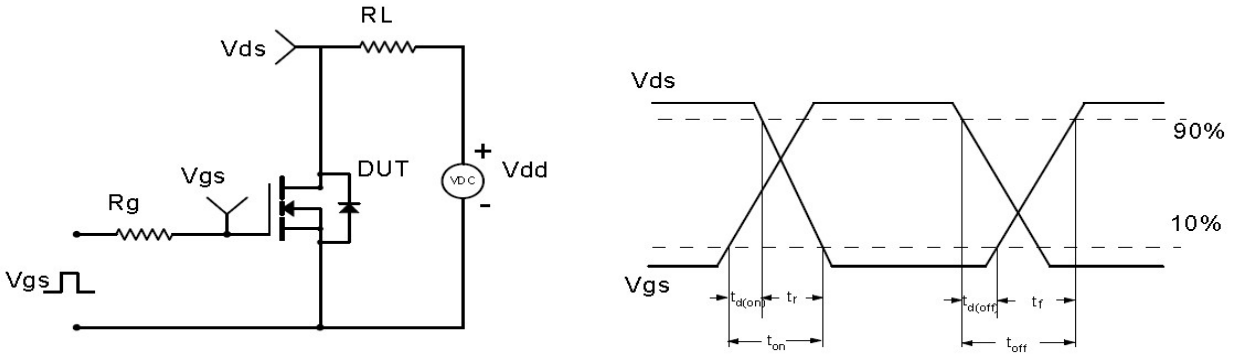
©China Resources Microelectronics (Chongqing) Limited

Test Circuit & Waveform

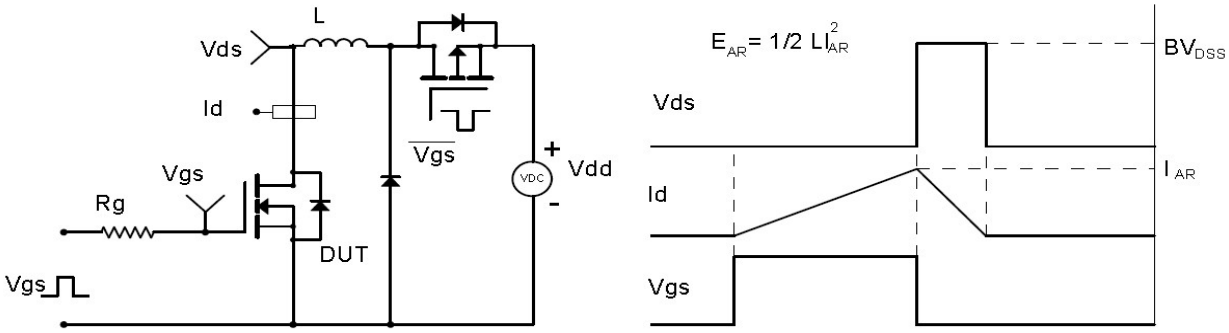
Gate Charge Test Circuit & Waveform



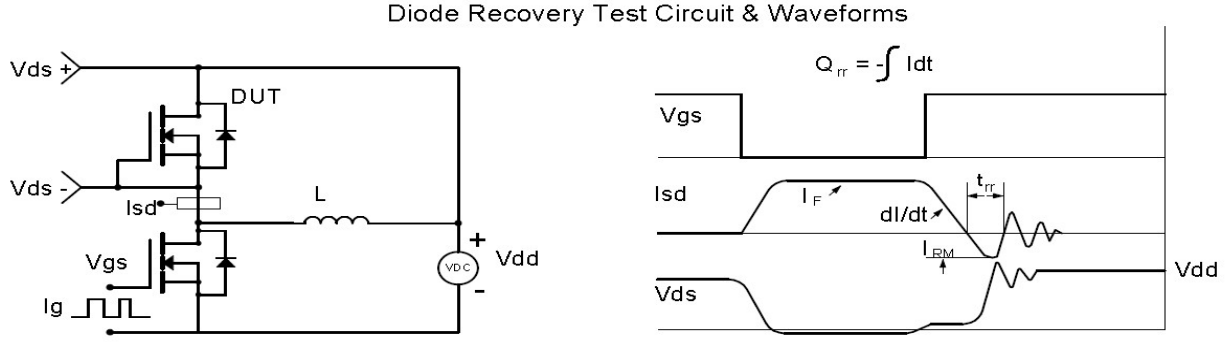
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

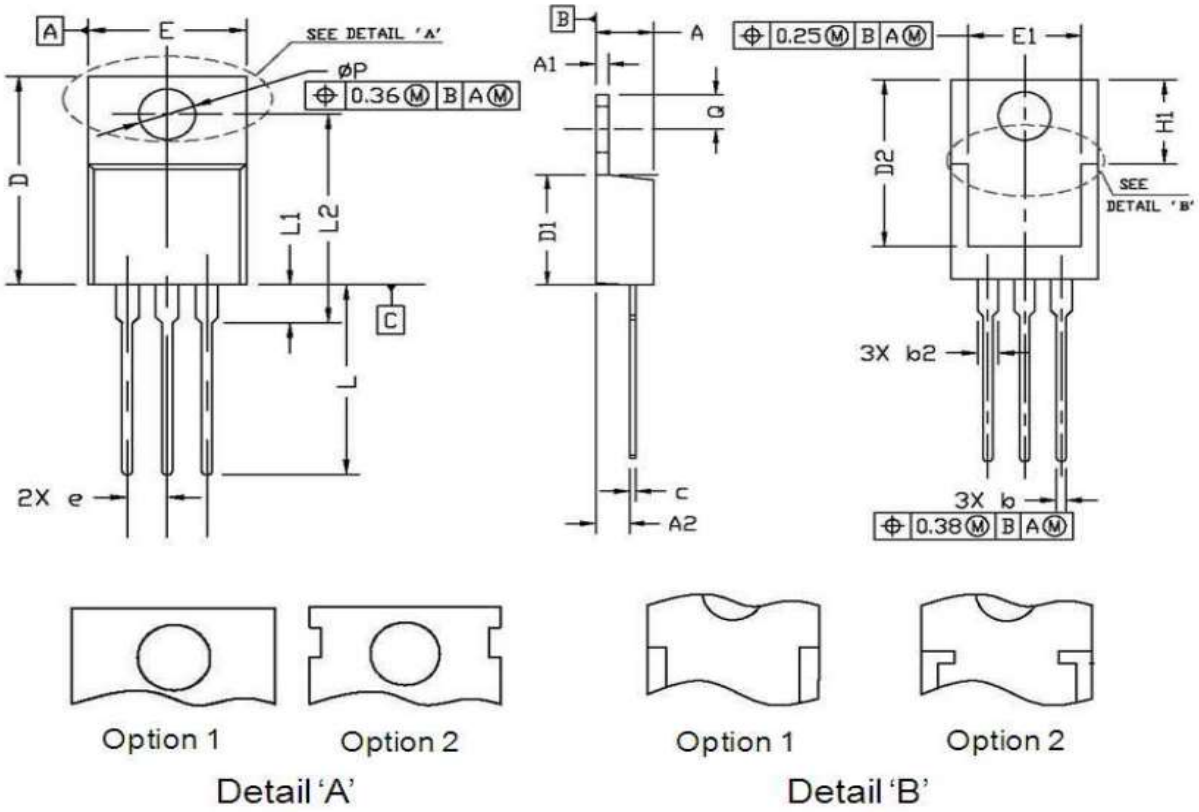


Diode Recovery Test Circuit & Waveforms



©China Resources Microelectronics (Chongqing) Limited

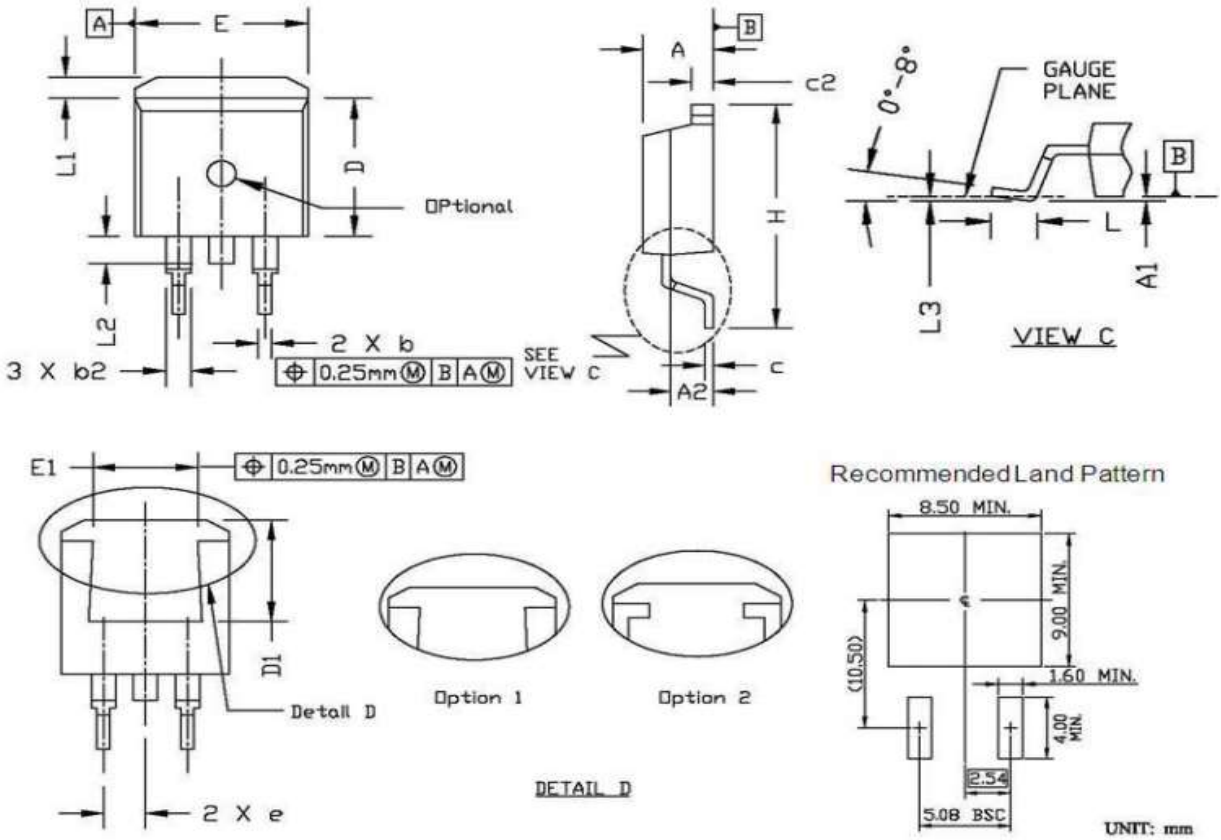
Package Outline: TO-220-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.30	4.80	0.169	0.189
A1	1.20	1.45	0.047	0.057
A2	2.20	2.90	0.087	0.114
b	0.69	0.95	0.027	0.037
b2	1.00	1.60	0.039	0.063
c	0.33	0.65	0.013	0.026
D	14.70	16.20	0.579	0.638
D1	8.59	9.65	0.338	0.380
D2	11.75	13.60	0.463	0.535
e	2.54 BSC.		0.100 BSC.	
E	9.60	10.60	0.378	0.417
E1	7.00	8.46	0.276	0.333
H1	6.20	7.00	0.244	0.276
L	12.60	14.80	0.496	0.583
L1	2.70	3.80	0.106	0.150
L2	12.13	16.50	0.478	0.650
Q	2.40	3.10	0.094	0.122
P	3.50	3.90	0.138	0.154

©China Resources Microelectronics (Chongqing) Limited

Package Outline: TO-263



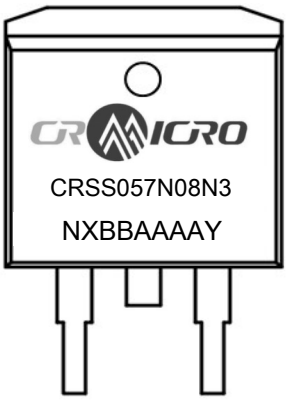
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.30	4.86	0.169	0.191
A1	0.00	0.25	0.000	0.010
A2	2.34	2.79	0.092	0.110
b	0.68	0.94	0.027	0.037
b2	1.15	1.35	0.045	0.053
c	0.33	0.65	0.013	0.026
c2	1.17	1.40	0.046	0.055
D	8.38	9.45	0.330	0.372
D1	6.90	8.17	0.272	0.322
e	2.54 BSC.		0.100 BSC.	
E	9.78	10.50	0.385	0.413
E1	6.50	8.60	0.256	0.339
H	14.61	15.88	0.575	0.625
L	2.24	3.00	0.088	0.118
L1	0.70	1.60	0.028	0.063
L2	1.00	1.78	0.039	0.070
L3	0.00	0.25	0.000	0.010

Marking



©China Resources Microelectronics (Chongqing) Limited





NOTE:
NXBBAAAAY

N	—Wire Bond code
X	—Assembly location code
BB	—Fab code
AAAA	—Lot code
Y	—Bin code

©China Resources Microelectronics (Chongqing) Limited

Revision History

Revison	Date	Major changes
1.0	2020-4-19	Official version;
2.0	2021-9-3	update package outline;

Disclaimer

Unless otherwise specified in the datasheet, the product is designed and qulified as a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability, such as automotive, aviation/aerospace and life-support devices or systems.

Any and all semicondutor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.

CRM(CQ) reserves the right to improve product design, function and reliability without notice.

©China Resources Microelectronics (Chongqing) Limited